# **BGA Heat Sink - High Performance ASIC Cooling**





ATS Part#: ATS-56009-C1-R0

Description: 58.00 x 30.00 x 9.00 mm BGA Heat Sink - High Performance ASIC Cooling

Heat Sink Type: ASIC Cooling
Heat Sink Attachment: Thermal Tape
Equivalent Part Number: ATS-56009-C3-R0

\*Image above is for illustration purpose only.

#### **Features & Benefits**

- maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- Designed specifically for ASIC package and their unique cooling requirements
- · Comes preassembled with high performance thermal interface material

#### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	4.8 °C/W	3.9 °C/W	3.1 °C/W	2.7 °C/W	2.4 °C/W	2.3 °C/W	2.2 °C/W
	Ducted Flow	2.4	N/A	N/A	N/A	N/A	N/A	N/A

### **Product Detail**

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish			
	58.00 mm	30.00 mm	9.00 mm	44.3 mm	T412	BLACK-ANODIZED			
	<ul> <li>Notes:</li> <li>Dimension A and B refer to component size.</li> <li>Dimension C is the heat sink height from the bottom of the base to the top of the fin field.</li> <li>ATS-56009-C3-R0 is the exact heat sink assembly with an equivalent thermal interface material (Saint-Gobain C675).</li> <li>Thermal performance data are provided for reference only. Actual performance may vary by application.</li> <li>ATS reserves the right to update or change its products without notice to improve the design or performance.</li> <li>ATS certifies that this heat sink assembly is RoHS-6 and REACH compliant.</li> <li>Contact ATS to learn about custom options available.</li> </ul>								
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